

Product and Process Change Notice

PCN No.	PCN02996	PCN Date	1/22/2018	Effective Date	4/23/2018
Title	Qualification of ChipMOS as an Assembly Site for DFN small flag Package				

Type: Major Change

Everspin is adding ChipMOS as a qualified assembly site for the DFN small flag package for SPI interface products.

Reason For Change

To increase capacity and improve supply flexibility.

Affected Products

Part Number	Description	Part Number	Description
MR20H40CDF	Industrial Temp.	MR20H40CDFR	Industrial Temp., T&R
MR25H40CDF	Industrial Temp.	MR25H40CDFR	Industrial Temp., T&R
MR25H40VDF	Extended Temp.	MR25H40VDFR	Extended Temp., T&R
MR25H40MDF	Automotive Grade 1	MR25H40MDFR	Automotive Grade 1, T&R
MR25H10CDF	Industrial Temp.	MR25H10CDFR	Industrial Temp., T&R
MR25H10MDF	Automotive Grade 1	MR25H10MDFR	Automotive Grade 1, T&R
MR25H256CDF	Industrial Temp.	MR25H256CDFR	Industrial Temp., T&R
MR25H256MDF	Automotive Grade 1	MR25H256MDFR	Automotive Grade 1, T&R
MR25H256ACDF	Industrial Temp.	MR25H256ACDFR	Industrial Temp., T&R
MR25H256AMDF	Automotive Grade 1	MR25H256AMDFR	Automotive Grade 1, T&R
MR25H256APDF	Automotive Grade 3	MR25H256APDFR	Automotive Grade 3, T&R
MR25H128ACDF	Industrial Temp.	MR25H128ACDFR	Industrial Temp., T&R
MR25H128APDF	Automotive Grade 3	MR25H128APDFR	Automotive Grade 3, T&R
MR25H128AMDF	Automotive Grade 1	MR25H128AMDFR	Automotive Grade 1, T&R

Impact on Form, Fit, Function, Quality or Reliability

No impact

Proposed First Ship Date for Change:

April 23, 2018

Key Material Differences

Material	Site	
	ChipMos	Amkor
Mold Compound	SUMITOMO EME-G631H	SUMITOMO EME-G700
BLT1 Epoxy	Hitachi 4900GC	Sumitomo CRM-1085A
BLT2 Epoxy	EM-710	Henkel ATB-120A DAF
BLT3 Epoxy	Henkel QMI550	Henkel Ablebond 8900NC

Product Identifier

Assembly site code = H for ChipMOS Taiwan

Supplier Qual Plan Schedule and Results

ChipMOS assembly line qualification is complete and all Everspin requirements met; a qualification report is available on request.

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Date Qualification Samples Are Available:

Samples are generally available now but please request your specific part number to your Everspin Sales contact.

Acceptance of Change

Everspin will consider this change accepted unless specific conditions for acceptance are provided in writing within 30 days of receipt of this notice.

Contact Information		Sample Information ☒ Samples Available Now
Joe O'Hare Director, Product Marketing Everspin Technologies joe.ohare@everspin.com (512) 828-3357		Contact Everspin sales: http://www.everspin.com/contact-us-everspin-technologies If using the on-line sample request please refer to this PCN # to receive samples.
Originator		
<u>Date</u> 1/22/2018	<u>Title</u> Marketing Director	<u>Name</u>  Joe O'Hare
Approval and Release		
<u>Date</u> 1/22/2018	<u>Title</u> Quality Engineer	<u>Name</u> Paul Drobny
<u>Date</u> 1/22/2018	<u>Title</u> VP of Sales	<u>Name</u> Annie Flaig
<u>Date</u> 1/22/2018	<u>Title</u> VP of Operations	<u>Name</u> Norm Armour